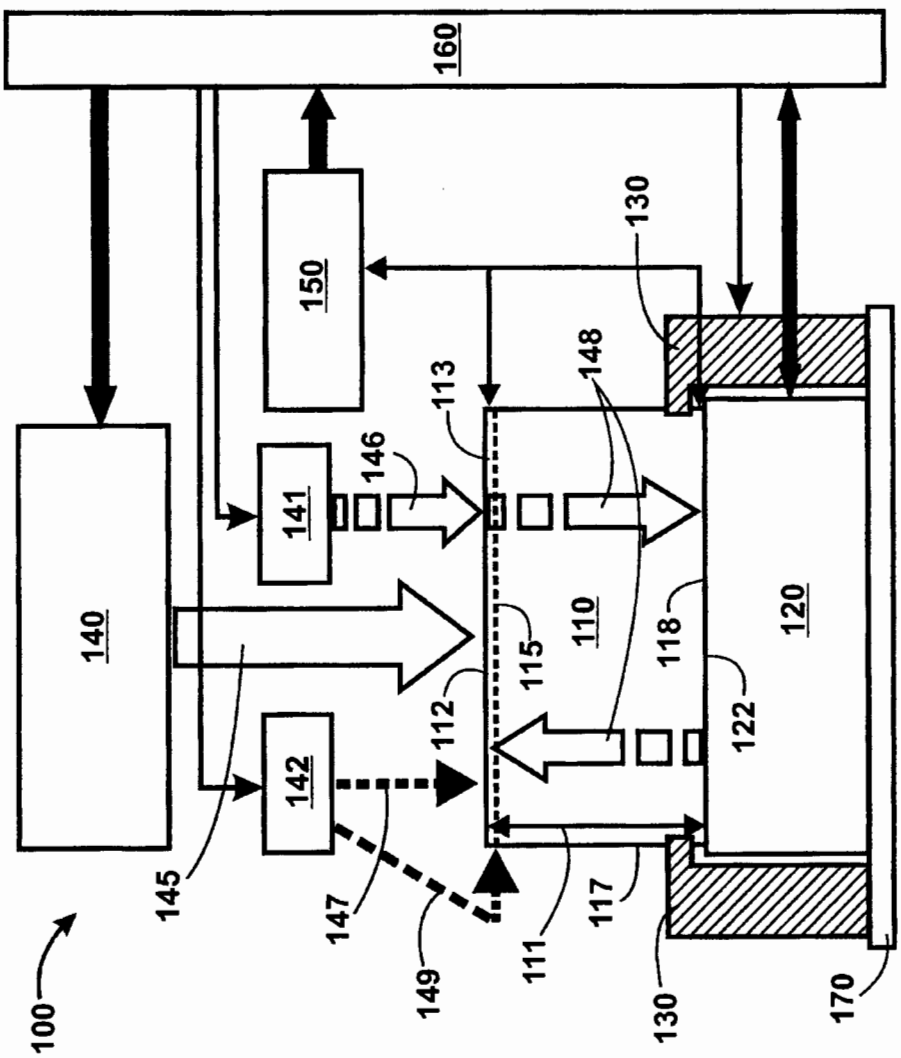

160
150
130
148
113
146
141
140
110
115
118
120
112
122
142
145
147
149
111
117
130
170
100

FIGURE 1

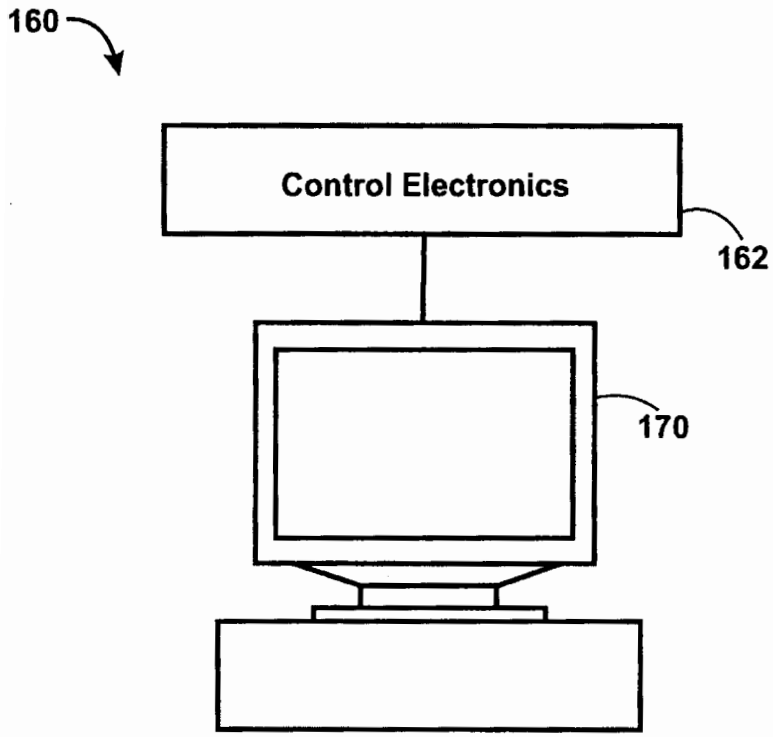


FIGURE 1A

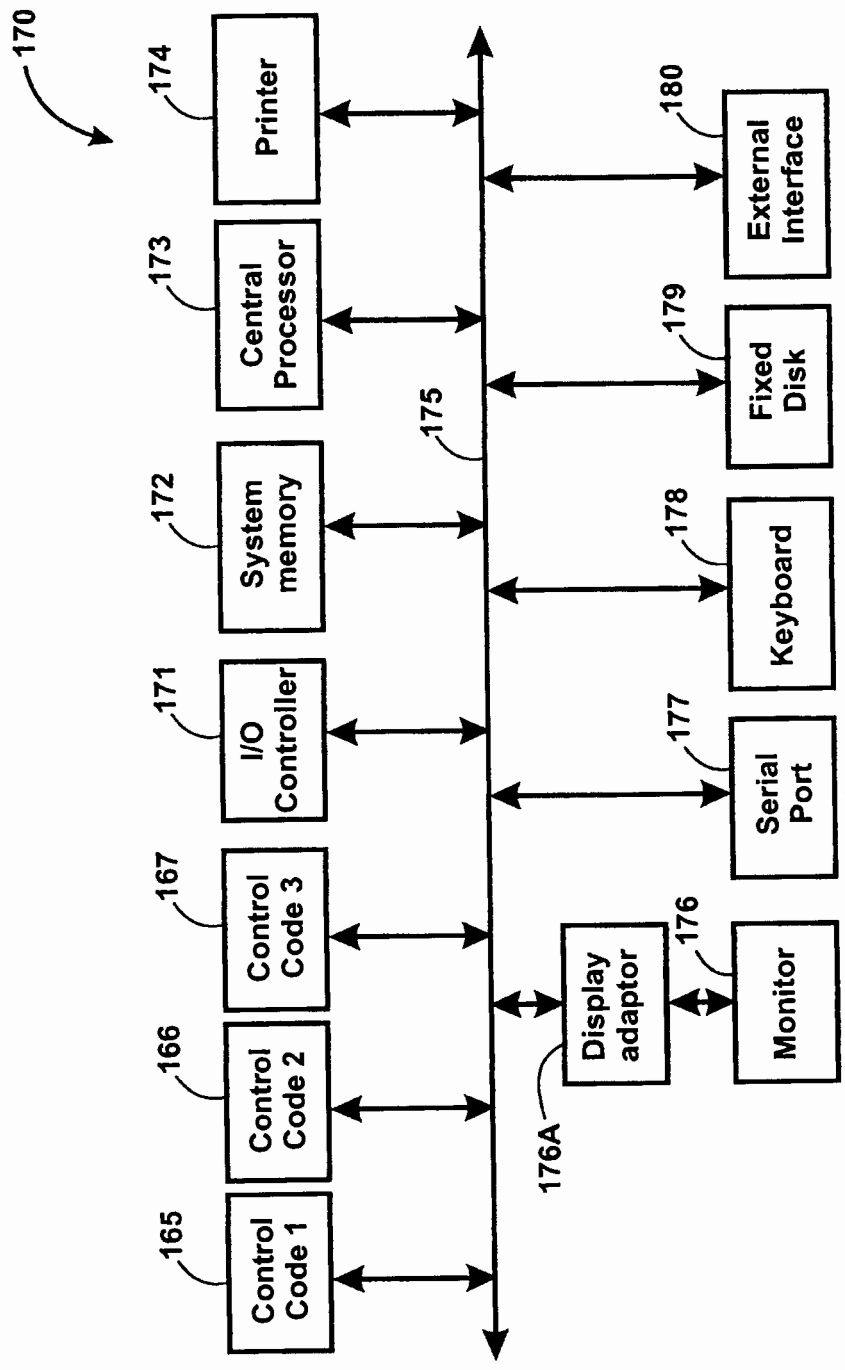

170
174
Printer
173
Central Processor
172
System memory
171
I/O Controller
167
Control Code 3
166
Control Code 2
165
Control Code 1
175
176A
Display adaptor
176
Monitor
177
Serial Port
178
Keyboard
179
Fixed Disk
180
External Interface

FIGURE 1B

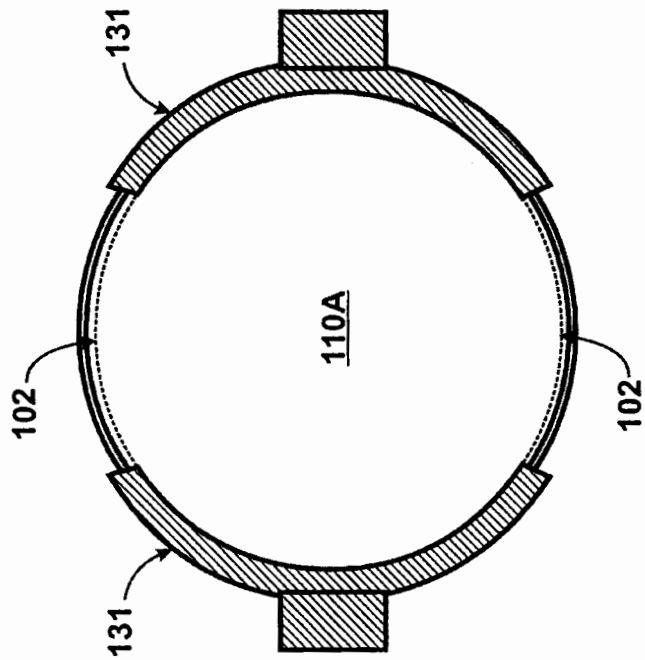


FIGURE 2B

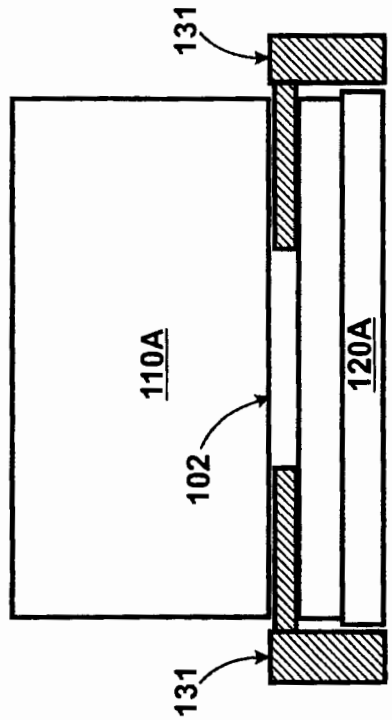


FIGURE 2A

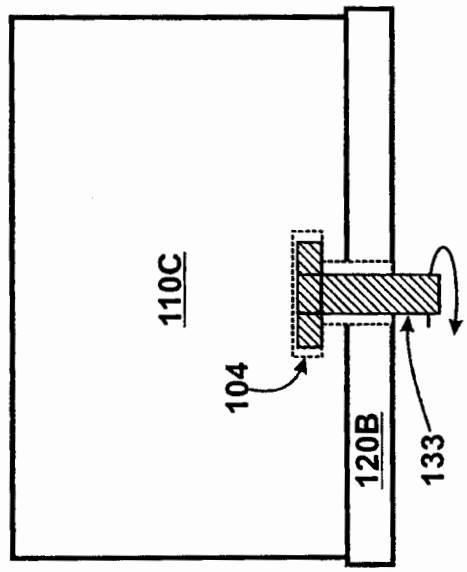


FIGURE 2D

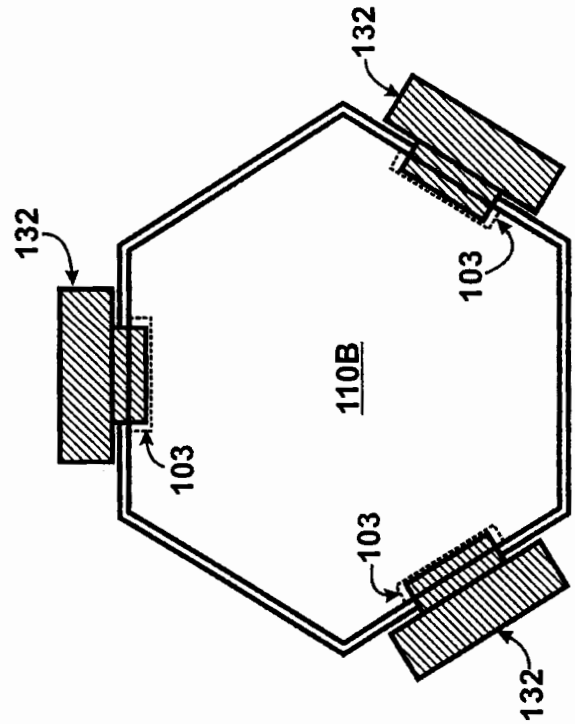


FIGURE 2C

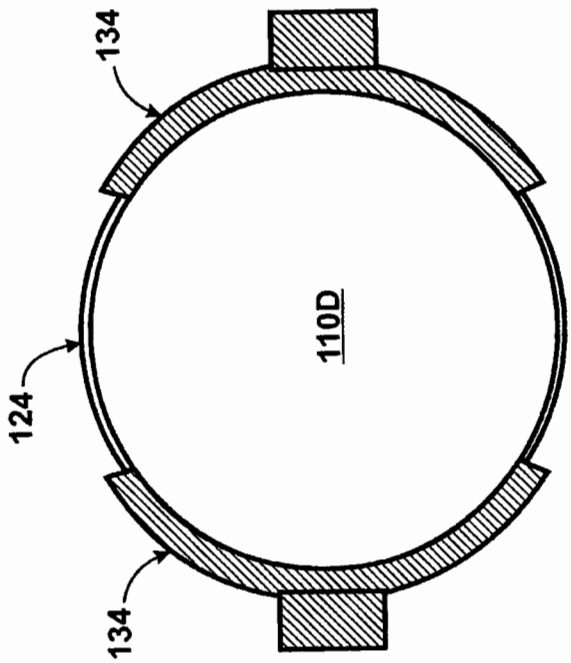


FIGURE 2F

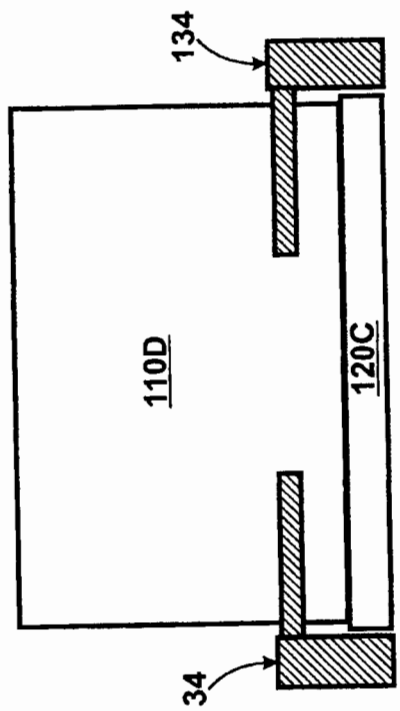


FIGURE 2E

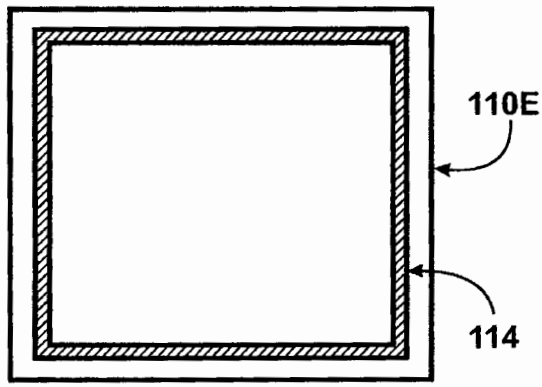


FIGURE 3

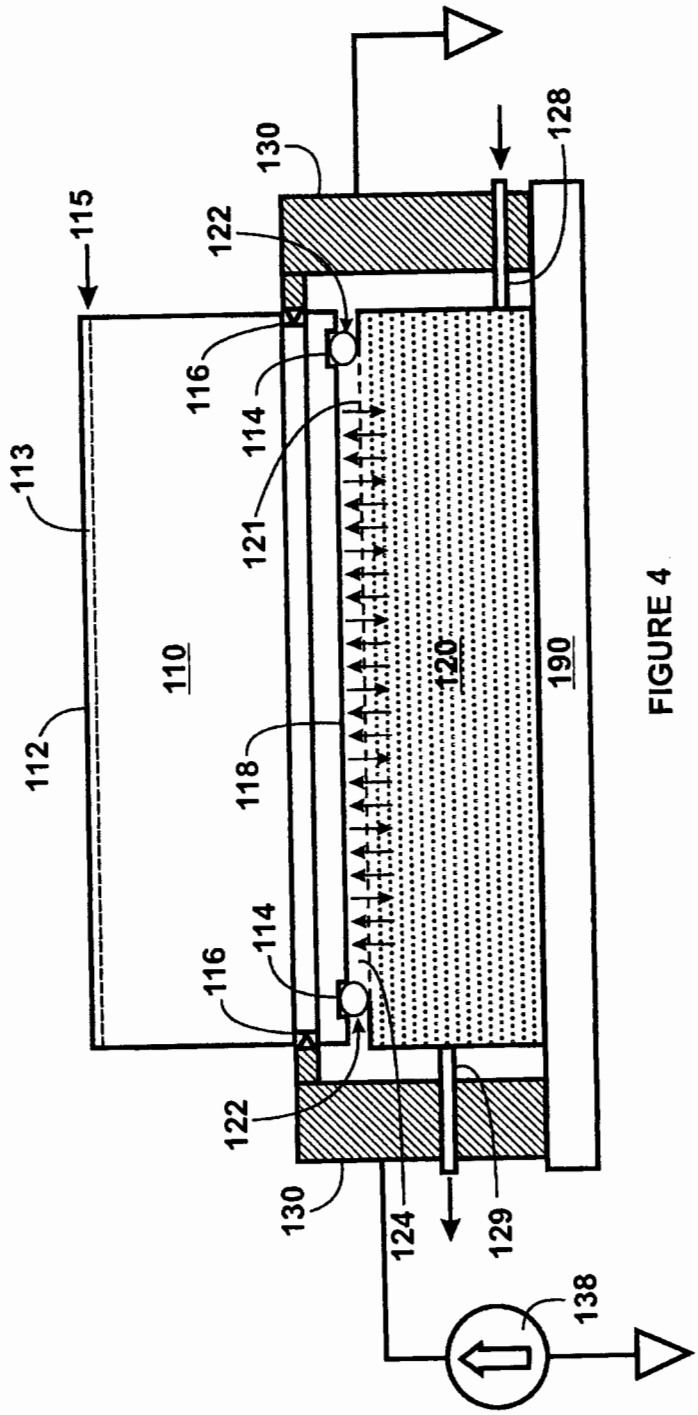


FIGURE 4

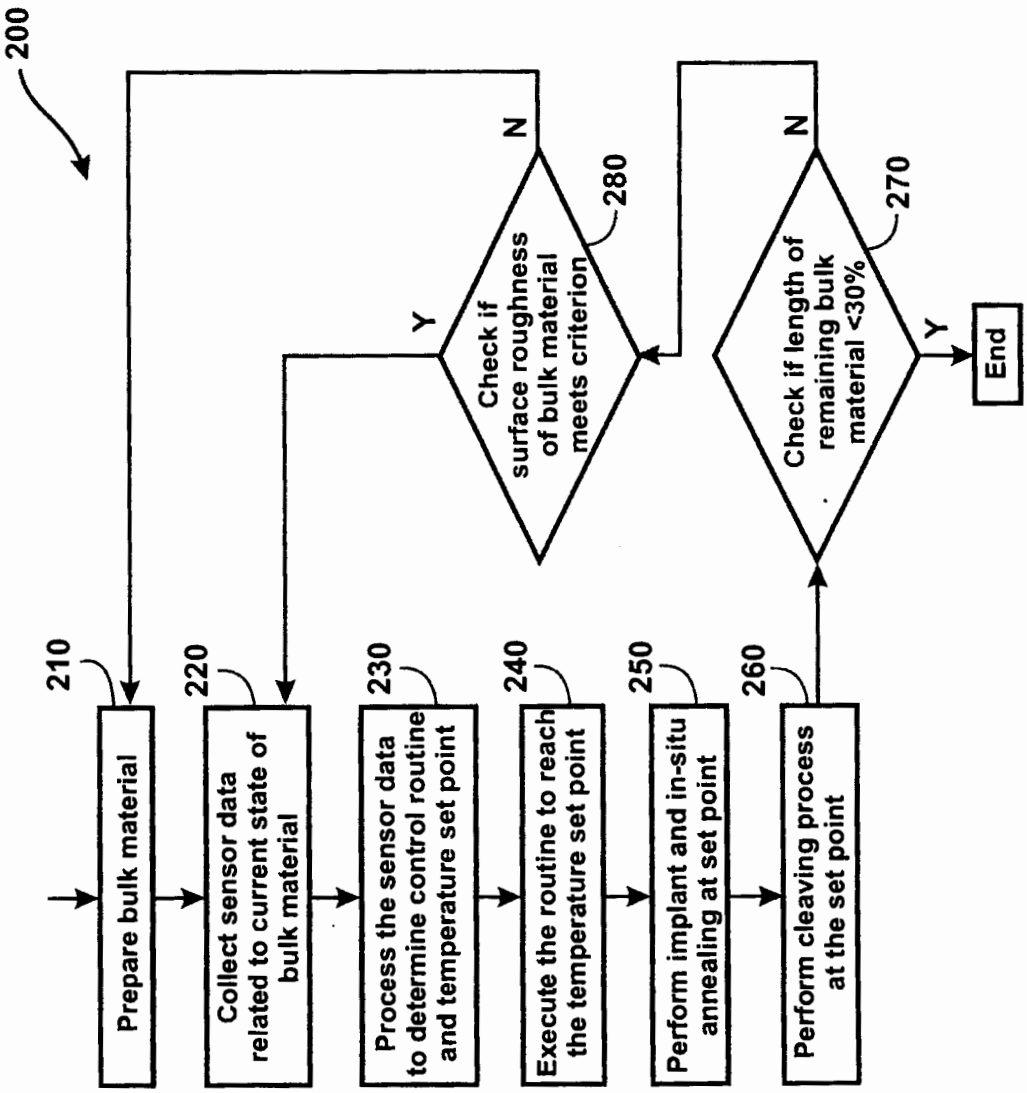

200
210
Prepare bulk material
220
Collect sensor data related to current state of bulk material
230
Process the sensor data to determine control routine and temperature set point
240
Execute the routine to reach the temperature set point
250
Perform implant and in-situ annealing at set point
260
Perform cleaving process at the set point
270
Check if length of remaining bulk material <30%
N
Y
280
Check if surface roughness of bulk material meets criterion
N
Y
End

FIGURE 5

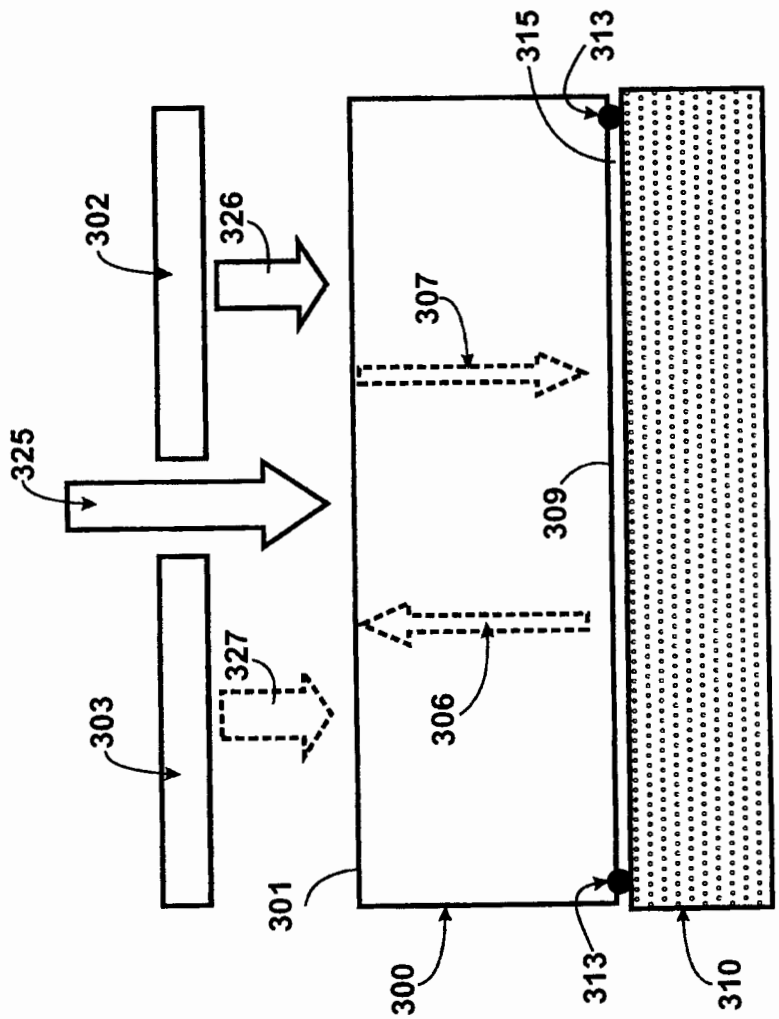


FIGURE 6

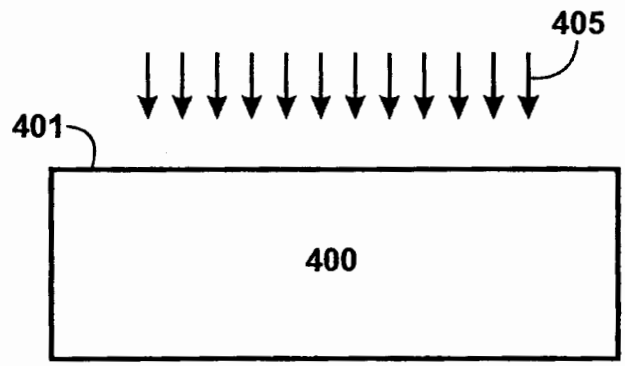


FIGURE 7

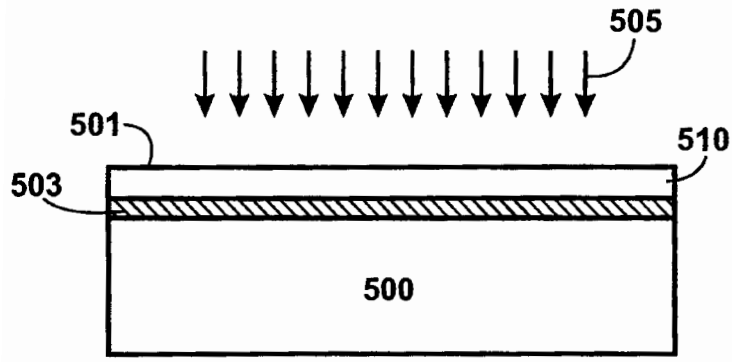


FIGURE 8

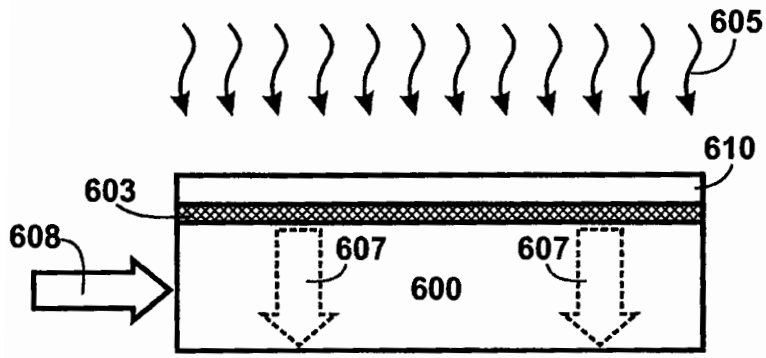


FIGURE 9

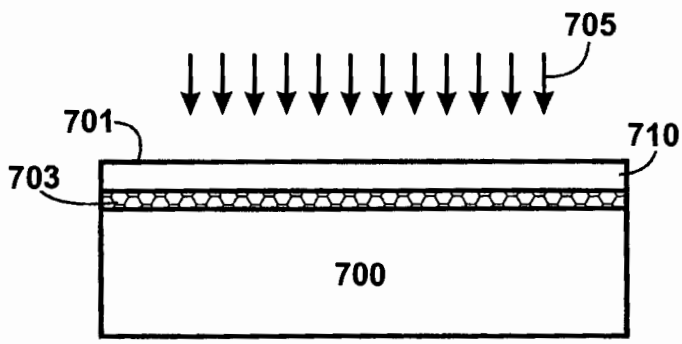


FIGURE 10

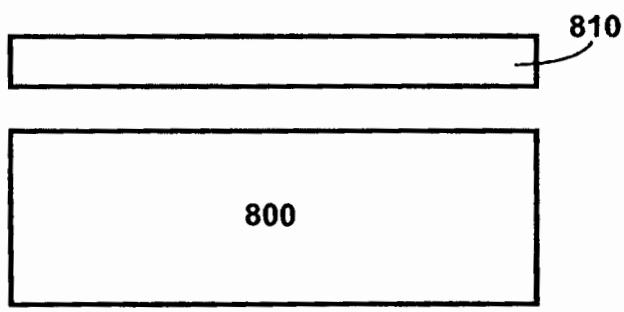


FIGURE 11

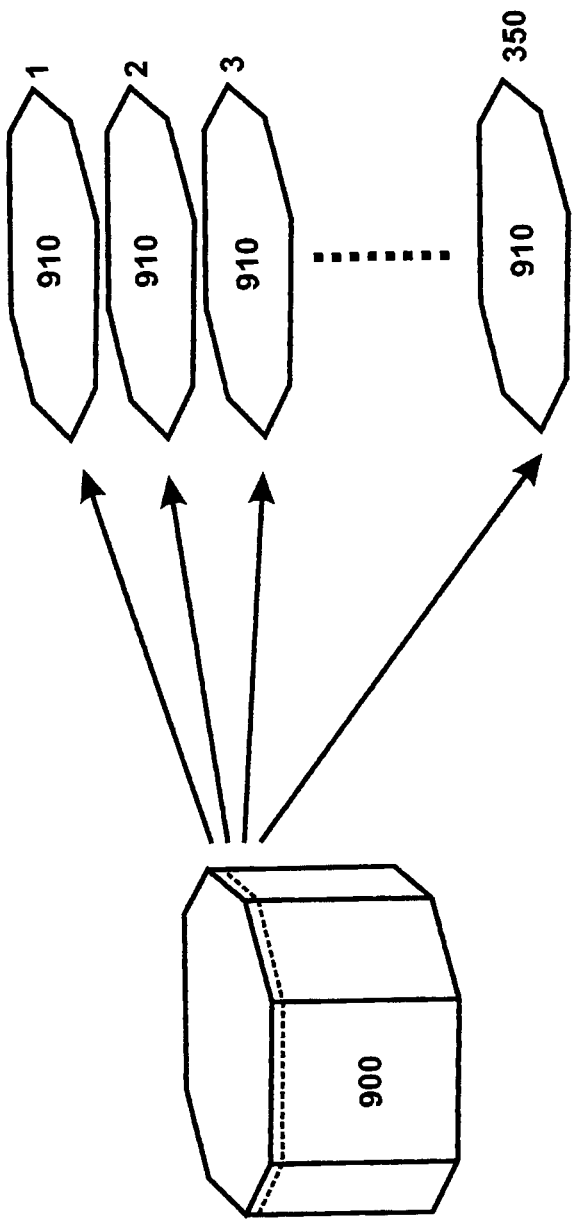


FIGURE 12

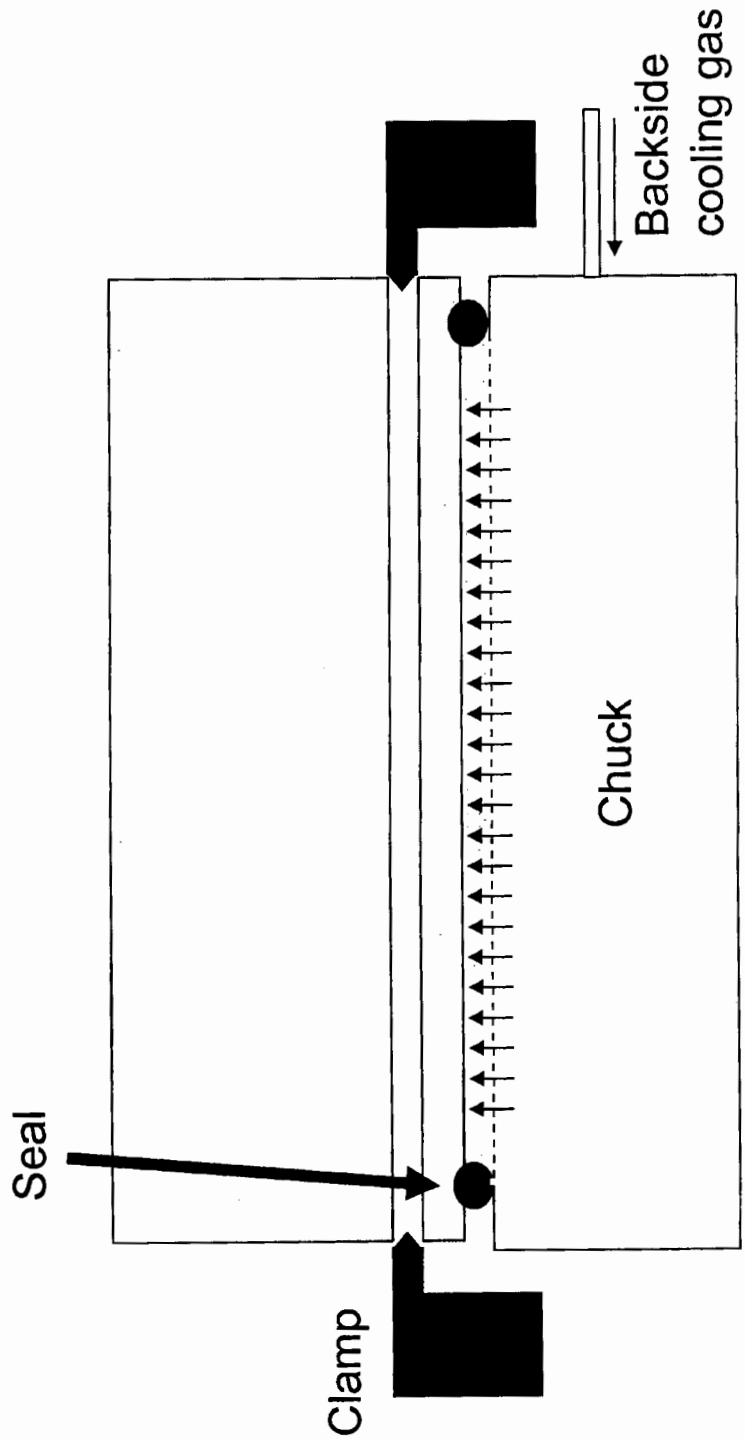


FIG. 13A

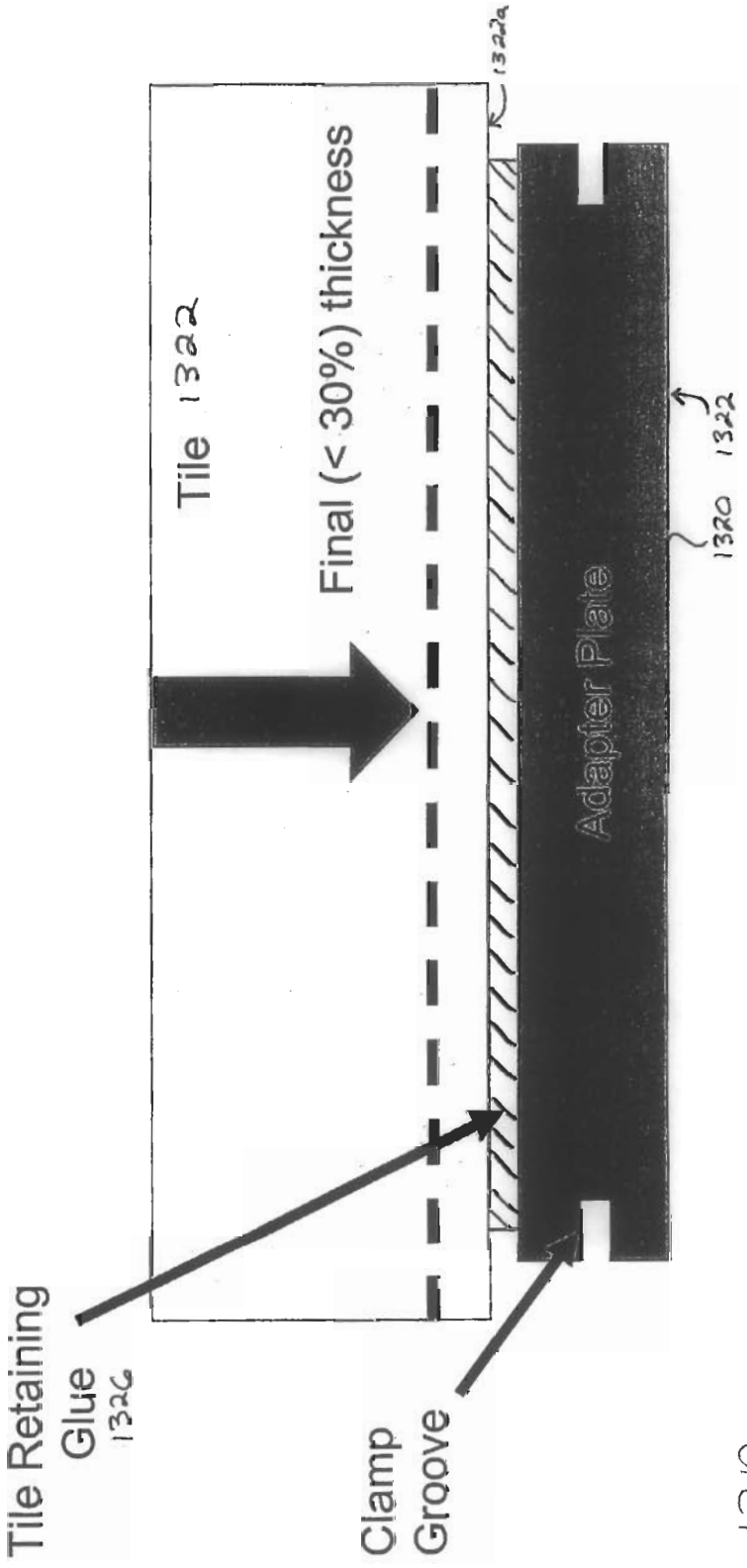

Tile 1322
Final (< 30%) thickness
1322a
Adapter Plate
1320
1322
Tile Retaining Glue 1326
Clamp Groove

FIG. 13B

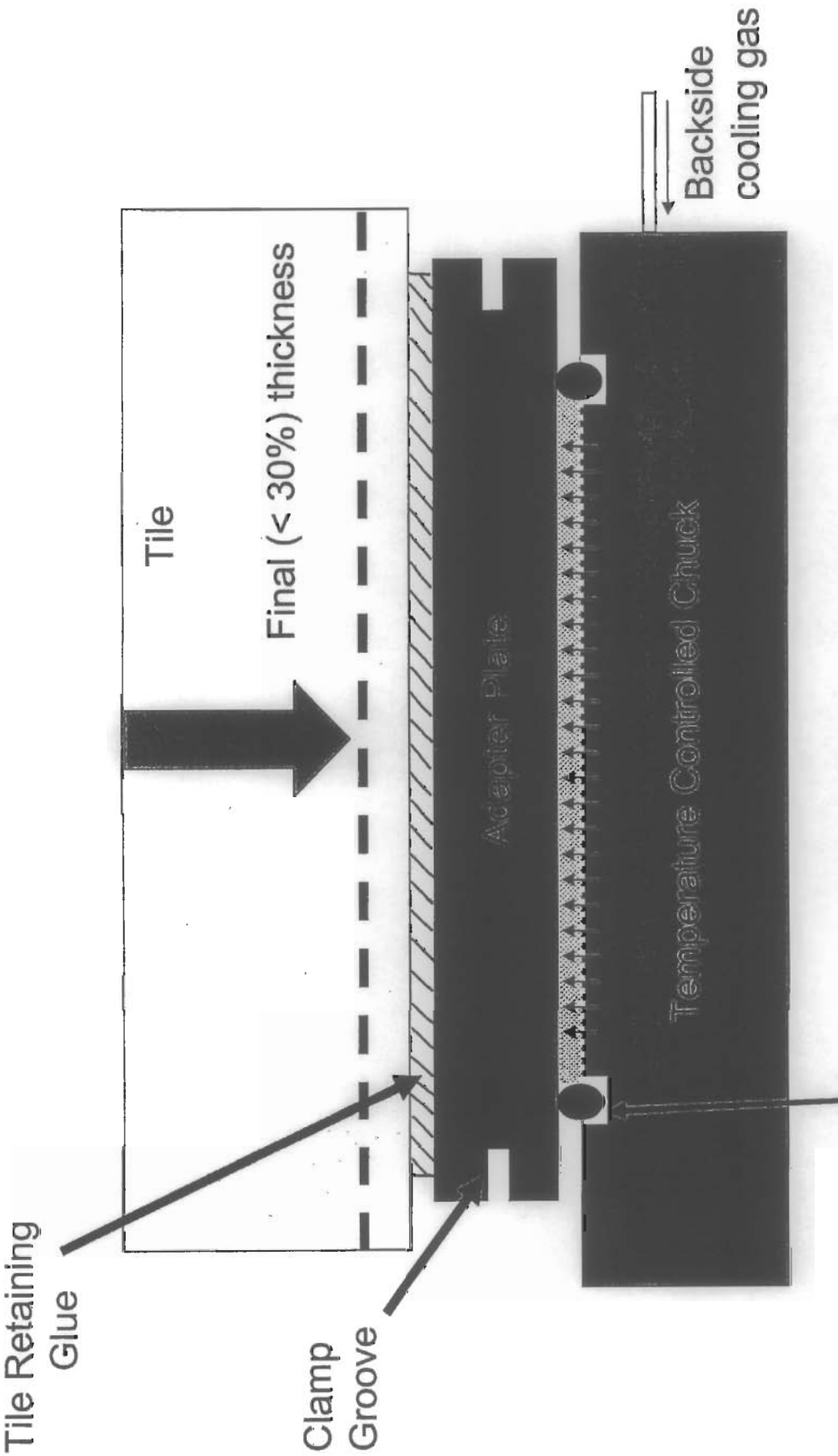

Tile Retaining Glue
Clamp Groove
Tile
Final (< 30%) thickness
Adapter Plate
Temperature Controlled Chuck
Backside cooling gas
Groove for cooling gas seal

FIG. 13C

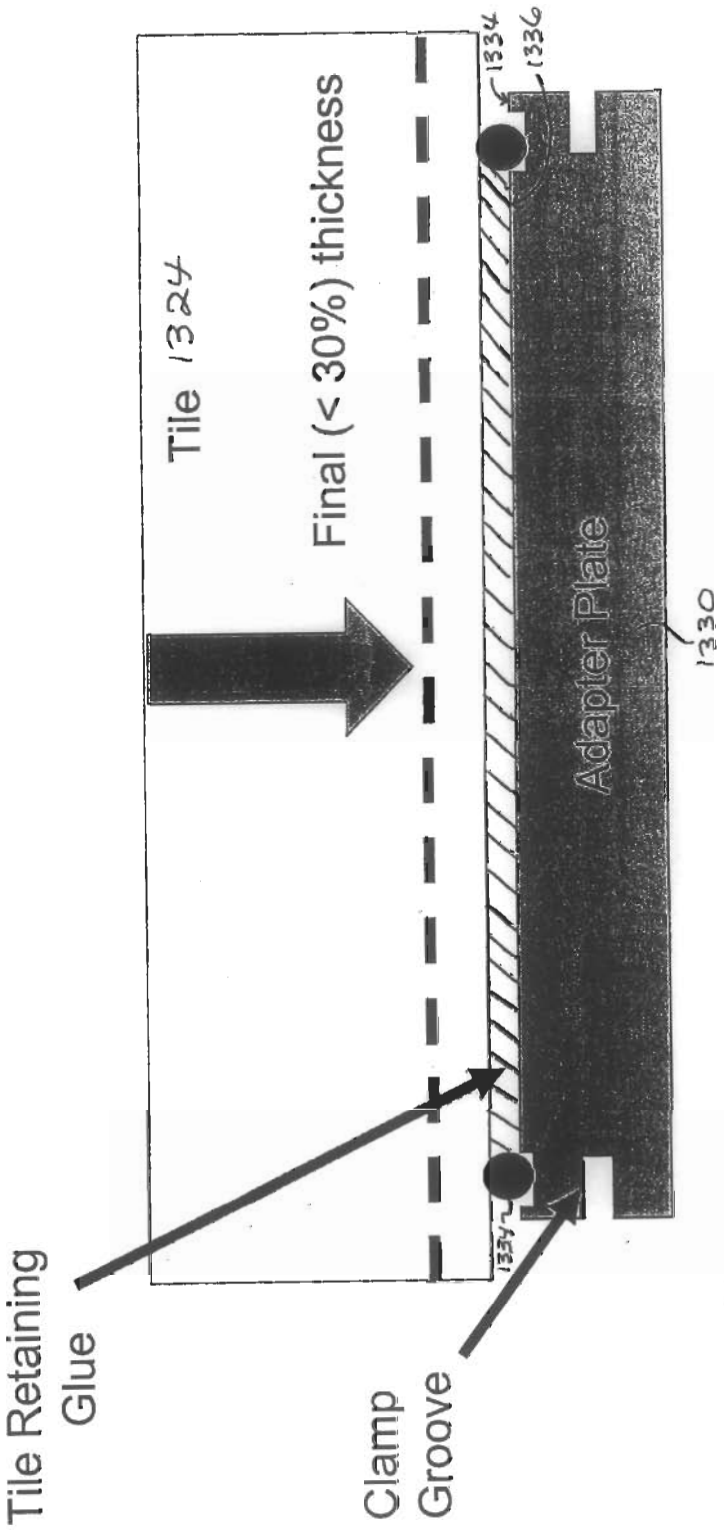

Tile 1324
Final (< 30%) thickness
Adapter Plate
1330
1334
1336
1337
Tile Retaining Glue
Clamp Groove

FIG. 13D

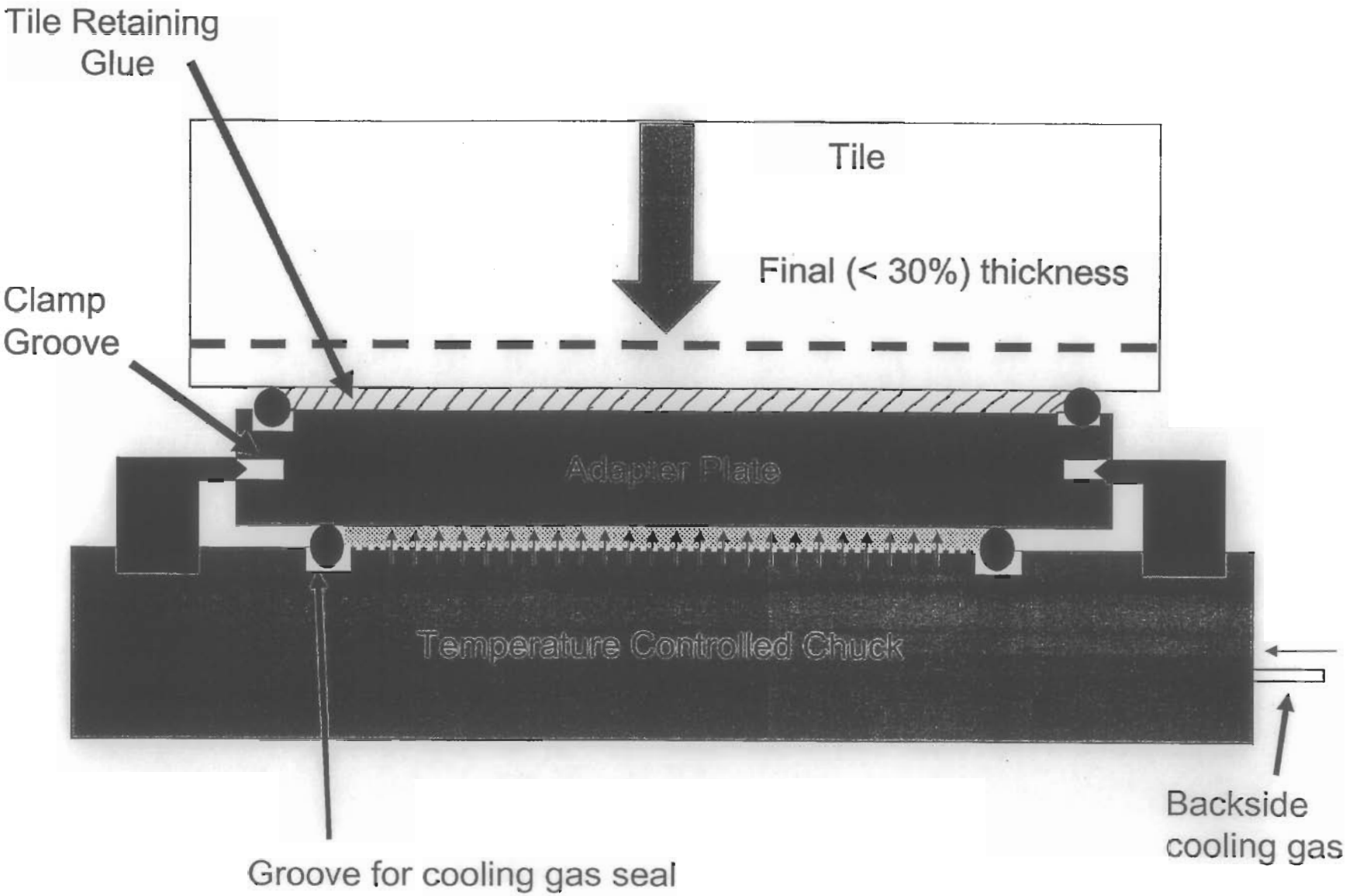

Tile Retaining Glue
Tile
Final (< 30%) thickness
Clamp Groove
Adapter Plate
Temperature Controlled Chuck
Backside cooling gas
Groove for cooling gas seal

FIG. 13E